

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 to 19 (canceled).

Claim 20 (currently amended): A device package, comprising:

a first wafer;

a second wafer; and

a perimeter of an intermetallic mixture interposed between the first and the second wafers, the intermetallic mixture bonding the first and the second wafers, the intermetallic mixture comprising materials from a reactive foil and a bonding material, the intermetallic mixture being formed after an exothermic reaction of the reactive foil.

Claim 21 (currently amended): A device package, comprising:

a first wafer;

a second wafer;

a perimeter of an intermetallic mixture interposed between the first and the second wafers, the intermetallic mixture comprising materials from a reactive foil and a bonding material, the intermetallic mixture being formed after an exothermic reaction of the reactive foil;

~~The device package of claim 20, further comprising:~~

a device; and

a second intermetallic mixture interposed between the device and the first wafer, the second intermetallic mixture comprising materials from a second reactive foil and a second bonding material, the second intermetallic mixture being formed after a second exothermic reaction of the second reactive foil.

Claim 22 (original): The device package of claim 20, wherein the second wafer comprises a feature selected from the group consisting of a hole and a cavity.

Claim 23 (currently amended): A device package, comprising:

a first wafer;

a second wafer;

a perimeter of an intermetallic mixture interposed between the first and the second wafers, the intermetallic mixture comprising materials from a reactive foil and a bonding material, the intermetallic mixture being formed after an exothermic reaction of the reactive foil;

~~The device package of claim 20, further comprising:~~

a third wafer; and

a second perimeter of a second intermetallic mixture interposed between the second and the third wafers, the second intermetallic mixture comprising materials from a second reactive foil and a second bonding material, the intermetallic mixture being formed after a second exothermic reaction of the second reactive foil.

Claims 24 and 25 (canceled).

Claim 26 (currently amended): A device wafer package, comprising:

a wafer having metal lines;

a device; and

an intermetallic mixture interposed between the device and the metal lines, the intermetallic mixture bonding the device and the metal lines, the intermetallic mixture comprising materials from a reactive foil and a bonding material, the intermetallic mixture being formed after an exothermic reaction of the reactive foil.

Claim 27 (original): The package of claim 26, wherein the device is selected from the group consisting a MEMS (micro-electromechanical systems) device, an electronic device, and an optoelectronic device.